



SMD Mount Receptacle

Part No:

RECE.20369.001E.01

Description:

SMD W.FL Compatible Receptacle

Compatible with I-PEX MHFIII. Hirose W.FL. Hirose W.FL2

Features:

Mating Height: 1.6mm Max

5000pcs per reel

Dimensions: 2 x 2 x 0.85 mm

Diameter: 1.4mm

RoHS & Reach Compliant



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Ireland & USA ISO 9001:2015 Certified















1. Introduction



Part of the Taoglas SMD Mount Receptacle the RECE.20369.001E.01 is a 3-pad type wire-to-board SMD Receptacle solution that is ultra-small, lightweight and low profile (1.6mm MAX.) with an operational frequency range of DC to 8 GHz. Taoglas the RECE.20369.001E.01 is gold plated to have superior performance and allow easy mounting of the male RF connector.

Packaged on tape and reel, this receptacle is designed to be placed with automatic "pick and place" equipment for ease of installation.

The RECE.20369.001E.01 acts as a 50 Ohm transmission line to connect the micro-miniature RF connector to the printed circuit board. It is fully compatible with I-PEX MHFIII, Hirose W.FL and all other available W.FL compatible connectors .

Applicable Technologies:

The RECE.20369.001E.01 receptacles are commonly integrated into GSM module, GPS module, Wireless LAN modules.

For further information, please contact your regional Taoglas customer support team.



2. Specifications

Electrical		
Operation Frequency	DC to 8 GHz	
VCMD	1.2 Max at DC~3 GHz	
VSWR	1.4 Max at 3~8 GHz	
Nominal Impedance	50 Ohm	
Rated Voltage	60V AC	
Rated Current	1A Max.	
Contact Resistance	Subject mated contacts assembled in housing to 20mV Max. open circuit at 10mA Max	
Withstand Voltage	AC 200V/minute	
Insulation Resistance	Impressed voltage 100V DC for 1min Initial : $500M\Omega$ Min. Final : $100M\Omega$ Min.	
Dielectric Withstanding Voltage	200V AC for 1 minute	
Current leakage	0.5mA Max	
Temperature	-40 to +90°C	

Material		
Outer Contact	Copper Alloy (Au plating)	
Centre Contact	Copper Alloy (Au plating)	
Insulator	LCP UL94-V0	

Environmental			
Durability per EIA-364-09C (2-3 cycles per min @ 30 cycles)			
Vibration	10Hz -> 100Hz -> 10Hz for 20 mins.		
Peak value of acceleration	1.5mm or 59m/s2 (6G)		
Direction	3 axis 5 Cycles		
Mechanical Shock			
Accelerate Velocity	735m/s2 (75G)		
Waveform	Half-sine shock plus.		
Duration	11m sec.		
Direct Current	1mA		
Direction	In ±X, ±Y and ±Z axes.		
Cycle	3 cycles for each direction, totally 18 cycles		

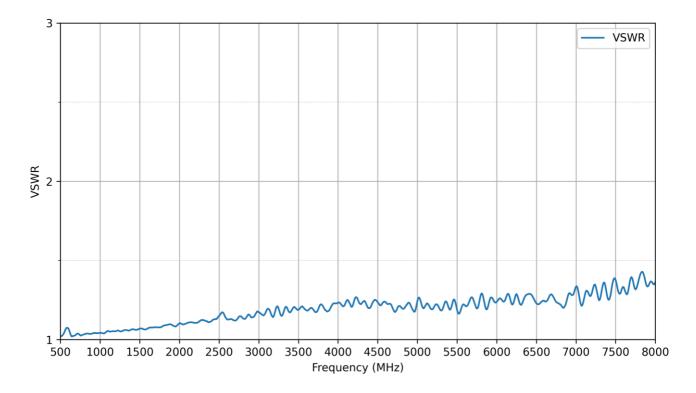


Thermal Shock (40°C for 30mins to 5~35°C for 5 minutes to 90°C for 30mins to 5~35°C for 5 minutes)		
Transition Time	5 minutes	
Cycles	5	
Humidity	90~95% RH	
Temperature	40+/- 2°C	
Duration	96 hours	
Salt Water Spray		
Temperature	35+/- 2°C	
Salt Water Density	5+/-1% (by weight)	
Duration	48 Hours	
High temperature life	90+/- 2°C for 96 hours	
Cold temperature life	-40+/- 2°C for 96 hours	
H2S gas		
Temperature	40+/-2°C	
Relative Humidity	80 +/-5% RH	
Gas H2S	3+/-1 ppm	
Duration	96 Hours	
Moisture Sensitivity Level	2	

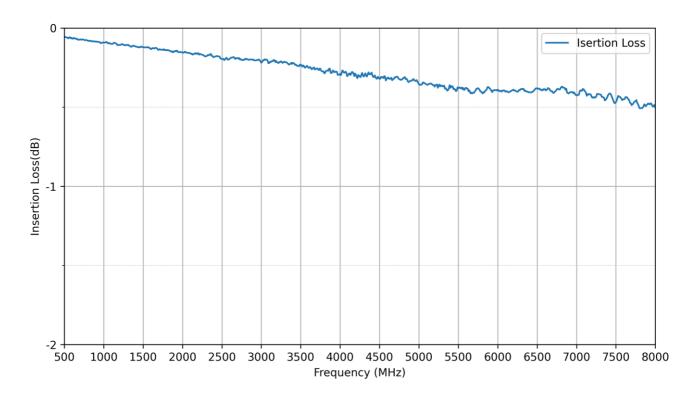


3. Connector Data

3.1 VSWR

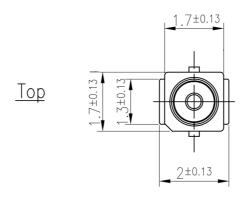


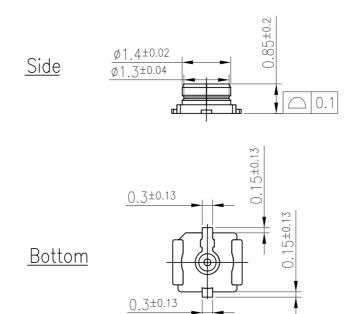
3.2 Insertion Loss

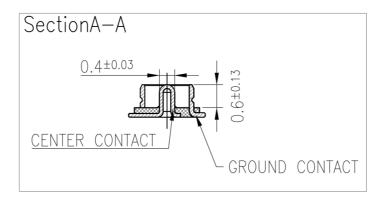




4. Mechanical Drawing (Units: mm)

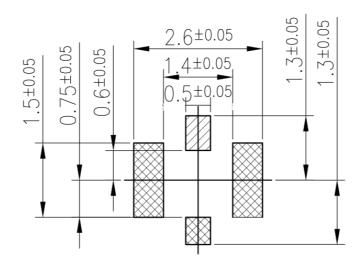








5. Footprint



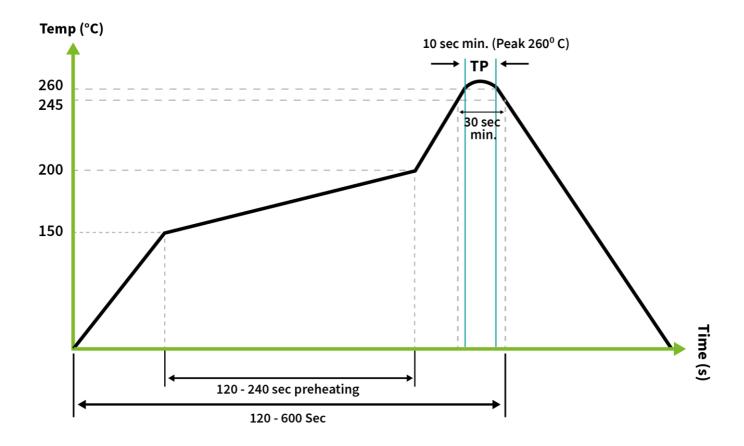
Notes:

1.CENTER CONTACT 2.GROUND CONTACT



6. Solder Reflow

The RECE.20369.001E.01 can be assembled by following the recommended soldering temperatures are as follows:



*Temperatures listed within a tolerance of +/- 10º C

Smaller components are typically mounted on the first pass, however, we do advise mounting the RECE.20369.001E.01 when placing larger components on the board during subsequent reflows.

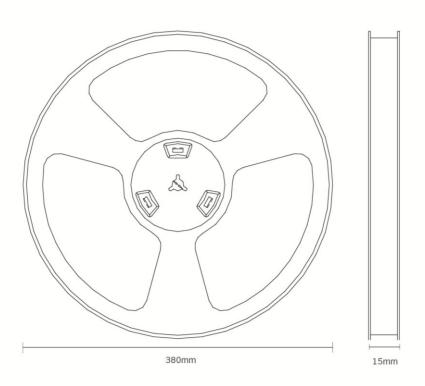
Note: Soldering flux classified ROLO under IPC J-STD-004 is recommended.

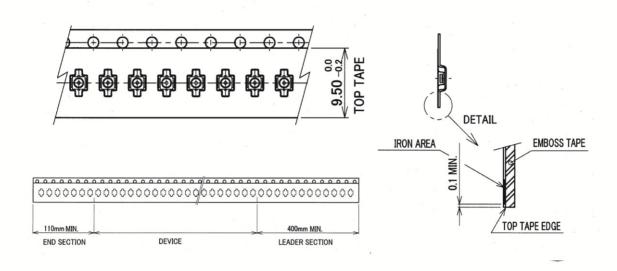


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Packaging

5000 pcs RECE.20369.001E.01 reel Dimensions - 380*380*15mm Weight -262g

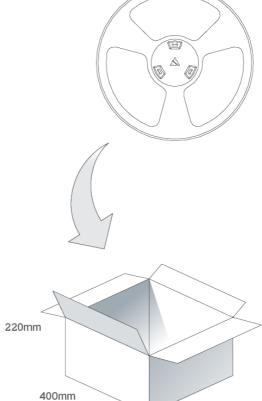




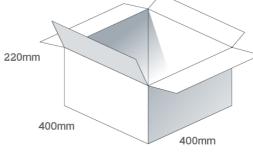


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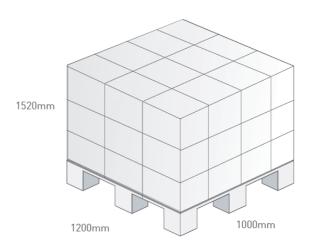
5000 pcs RECE.20369.001E.01 reel Dimensions - 380*380*15mm Weight - 262g



8 reels, 40000 pcs in one carton Carton Dimensions - 400*400*220mm Weight - 3.5Kg



Pallet Dimensions 1200*1000*1520mm 36 Cartons per Pallet 12 Cartons per layer 3 Layers



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Changelog for the datashee

SPE-16-8-033 - RECE.20369.001E.01

	2025-02-24 Updated graphs to show up to 8GHz.
Changes:	Updated graphs to show up to 8GHz.
Changes Made by:	Gary West

Previous Revisions

Revision: G	
Date:	2024-10-28
Changes:	Updated MSL from 3 to 2.
Changes Made by:	Paul Liu

Revision: C	
Date:	2021-07-15
Changes:	Updated Solder Reflow Diagram & Adding MSL.
Changes Made by:	Gary West

Revision: F	
Date:	2023-09-07
Changes:	Updated Solder Reflow Information
Changes Made by:	Cesar Sousa

Revision: B		
Date:	2021-02-03	
Changes:	Following EC-20-8-036	
Changes Made by:	Jack Conroy	

Revision: E		
Date:	2023-03-03	
Changes:	Updated description	
Changes Made by:	Cesar Sousa	

Revision: A (Original First Release)	
Date:	2016-04-21
Notes:	
Author:	Jack Conroy

Revision: D	
Date:	2022-01-27
Changes:	Updated Solder Reflow Diagram & Adding MSL.
Changes Made by:	Gary West





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